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4.8mm BI-LEVEL LED INDICATOR

Part Number: WP73EB/IGDA

High Efficiency Red

Features

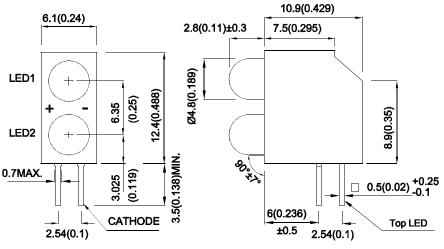
- Pre-trimmed leads for pc board mounting.
- Colors can be mixed in a single housing.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

Descriptions

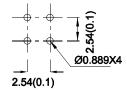
- The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.
- The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions

LED1: RED LED2: GREEN



RECOMMENDED PCB LAYOUT





- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
 4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SPEC NO: DSAM7395 **REV NO: V.3A** DATE: APR/12/2016 PAGE: 1 OF 6 **APPROVED: Wynec CHECKED: Allen Liu** DRAWN: M.Liu ERP: 1102001981

Selection Guide

Part No.	Emitting Color (Material)	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]
1 411.1101		zone rype	Min.	Тур.	201/2
WP73EB/IGDA	High Efficiency Red (GaAsP/GaP)	Red Diffused	15	40	60°
		Red Dillused	*8	*20	
	Green (GaP)	Green Diffused	10	30	- 60°
		Green Dinused	*10	*30	

Notes:

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

 2. Luminous intensity / luminous Flux: +/-15%.

 * Luminous intensity value is traceable to CIE127-2007 standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	High Efficiency Red Green	627 565		nm	IF=10mA	
λD [1]	Dominant Wavelength	High Efficiency Red Green	617 568		nm IF=10mA		
Δλ1/2	Spectral Line Half-width	High Efficiency Red Green	45 30		nm	IF=10mA	
С	Capacitance	High Efficiency Red Green	15 15		pF V _F =0V;f=1MHz		
VF [2]	Forward Voltage	High Efficiency Red Green	1.9 2	2.5 2.5	V	IF=10mA	
lR	Reverse Current	High Efficiency Red Green		10 10	uA	VR = 5V	

Notes:

- Wavelength: +/-1nm.
 Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to CIE127-2007 standards.
- 4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

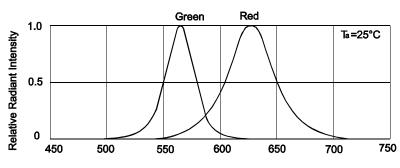
Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Green	Units		
Power dissipation	75	62.5	mW		
DC Forward Current	30	25	mA		
Peak Forward Current [1]	160	140	mA		
Reverse Voltage	5 V				
Operating / Storage Temperature	-40°C To +85°C				
Lead Solder Temperature [2]	260°C For 3 Seconds				
Lead Solder Temperature [3]	260°C For 5 Seconds				

Notes:

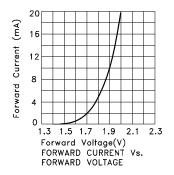
- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
- 2. 2mm below package base.
- 5mm below package base.
 Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

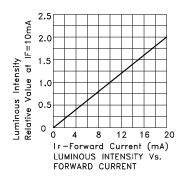
SPEC NO: DSAM7395 **REV NO: V.3A** DATE: APR/12/2016 PAGE: 2 OF 6 APPROVED: Wynec **CHECKED: Allen Liu** DRAWN: M.Liu ERP: 1102001981

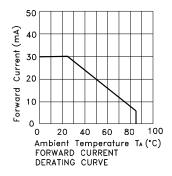


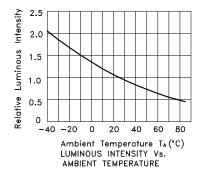
wavelength λ (nm) Relative Intensity Vs. Wavelength

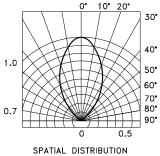
WP73EB/IGDA High Efficiency Red





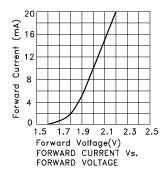


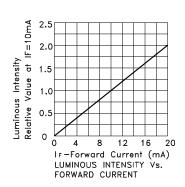


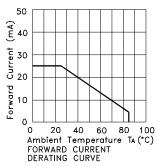


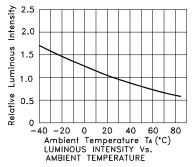
SPEC NO: DSAM7395 REV NO: V.3A DATE: APR/12/2016 PAGE: 3 OF 6
APPROVED: Wynec CHECKED: Allen Liu DRAWN: M.Liu ERP: 1102001981

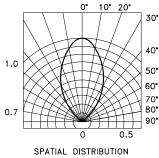
Green



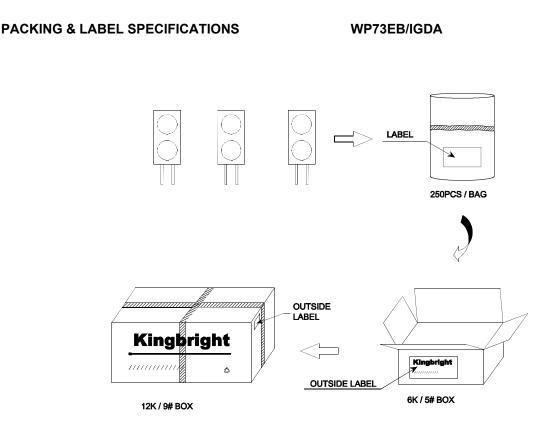








SPEC NO: DSAM7395 REV NO: V.3A DATE: APR/12/2016 PAGE: 4 OF 6
APPROVED: Wynec CHECKED: Allen Liu DRAWN: M.Liu ERP: 1102001981





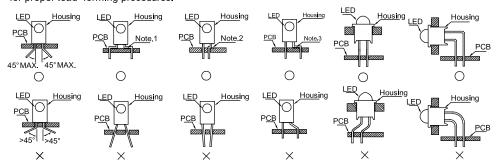
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SPEC NO: DSAM7395 REV NO: V.3A DATE: APR/12/2016 PAGE: 5 OF 6
APPROVED: Wynec CHECKED: Allen Liu DRAWN: M.Liu ERP: 1102001981

PRECAUTIONS

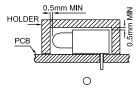
- 1. Storage conditions:
 - a. Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
 - b.LEDs should be stored with temperature ≤30°C and relative humidity < 60%.
 - c.Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 \sim 100°C.
- 2. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

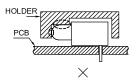


" \bigcirc " Correct mounting method " imes " Incorrect mounting method

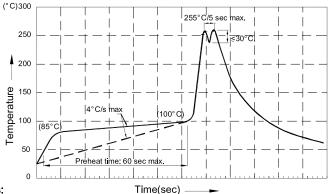
Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.





- 4. The tip of the soldering iron should never touch the lens epoxy.
- 5. Through-hole LEDs are incompatible with reflow soldering.
- If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 7. Recommended Wave Soldering Profiles:



- 1.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- 2.Peak wave soldering temperature between 245° C ~ 255° C for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85° C.
- 4. Fixtures should not incur stress on the component when mounting and during soldering process.
- 5.SAC 305 solder alloy is recommended.
- 6.No more than one wave soldering pass.

SPEC NO: DSAM7395 REV NO: V.3A DATE: APR/12/2016 PAGE: 6 OF 6
APPROVED: Wynec CHECKED: Allen Liu DRAWN: M.Liu ERP: 1102001981